

Description

The TPCC8093 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

V_{DS} = 20V I_D =60A

 $R_{DS(ON)} < 5m\Omega$ @ V_{GS}=4.5V

Application

Battery protection

Load switch

Uninterruptible power supply

Package Marking and Ordering Information

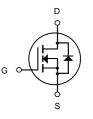
Product ID	Pack	Brand	Qty(PCS)
TPCC8093	DFN3X3-8L(TSON-8(3.1x3.3))	HXY MOSFET	5000

Absolute Maximum Ratings (TC=25°C unless otherwise specified)

Symbol	Parameter	Rating	Units
Vds	Drain-Source Voltage	20	V
Vgs	Gate-Source Voltage	±12	V
I⊳@Tc=25°C	Continuous Drain Current, V _{GS} @ 10V ¹	60	А
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ¹	33	А
Ідм	Pulsed Drain Current ²	220	А
EAS	Single Pulse Avalanche Energy ³	46	mJ
las	Avalanche Current	25	А
P₀@Tc=25°C	Total Power Dissipation ⁴	15	W
Тѕтд	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C
R ₀ JA	Thermal Resistance Junction-ambient ¹	62	°C/W
R _θ JC	Thermal Resistance Junction-Case ¹	4.5	°C/W



DFN3X3-8L (TSON-8(3.1x3.1))



N-Channel MOSFET



Parameter	Test Condition	Min.	Тур.	Max.	Units
Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250µA	20	-	-	V
Zero Gate Voltage Drain Current	V_{DS} =20V, V_{GS} =0V,	-	-	1.0	μA
Gate to Body Leakage Current	V_{DS} =0V, V_{GS} =±12V	-	-	±100	nA
Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_{D}=250\mu A$	0.4	0.7	1.1	V
Static Drain-Source on-Resistance	V _{GS} =4.5V, I _D =30A	-	4.0	5	mΩ
note3	V _{GS} =2.5V, I _D =20A	-	6.0	9	11122
Input Capacitance	V _{DS} =10V, V _{GS} =0V,	-	2500	-	pF
Output Capacitance		-	407	-	pF
Reverse Transfer Capacitance		-	386	-	pF
Total Gate Charge		-	32	-	nC
Gate-Source Charge		-	3	-	nC
Gate-Drain("Miller") Charge	VGS=4.3V	-	11	-	nC
Turn-on Delay Time	V _{DS} =10V,	-	17	-	ns
Turn-on Rise Time		-	49	-	ns
Turn-off Delay Time	- , ,	-	74	-	ns
Turn-off Fall Time	VGS -4.3V	-	26	-	ns
Maximum Continuous Drain to Source Diode Forward				75	•
Current		-	-	/5	A
Maximum Pulsed Drain to Source Diode Forward Current		-	-	300	А
Drain to Source Diode Forward					
	Drain-Source Breakdown Voltage Zero Gate Voltage Drain Current Gate to Body Leakage Current Gate Threshold Voltage Static Drain-Source on-Resistance note3 Input Capacitance Output Capacitance Reverse Transfer Capacitance Total Gate Charge Gate-Source Charge Gate-Drain("Miller") Charge Turn-on Delay Time Turn-on Rise Time Turn-off Delay Time Turn-off Fall Time Maximum Continuous Drain to Source Current Maximum Pulsed Drain to Source Dio	Drain-Source Breakdown Voltage $V_{GS}=0V, I_D=250\mu A$ Zero Gate Voltage Drain Current $V_{DS}=20V, V_{GS}=0V,$ Gate to Body Leakage Current $V_{DS}=0V, V_{GS}=\pm12V$ Gate Threshold Voltage $V_{DS}=V_{GS}, I_D=250\mu A$ Static Drain-Source on-Resistance note3 $V_{GS}=4.5V, I_D=30A$ Note3 $V_{GS}=2.5V, I_D=20A$ Input Capacitance $V_{DS}=10V, V_{GS}=0V,$ f = 1.0MHz $V_{DS}=10V, I_D=30A,$ Reverse Transfer Capacitance $V_{DS}=10V, I_D=30A,$ Gate-Source Charge $V_{DS}=10V, I_D=30A,$ Gate-Drain("Miller") Charge $V_{DS}=10V, I_D=30A,$ Turn-on Delay Time $V_{DS}=10V,$ Turn-off Delay Time $V_{DS}=10V,$ Turn-off Fall Time $V_{DS}=4.5V$ Maximum Continuous Drain to Source Diode Forward CurrentMaximum Pulsed Drain to Source Diode Forward Current	Drain-Source Breakdown Voltage $V_{GS}=0V, I_D=250\muA$ 20Zero Gate Voltage Drain Current $V_{DS}=20V, V_{GS}=0V,$ -Gate to Body Leakage Current $V_{DS}=0V, V_{GS}=\pm12V$ -Gate Threshold Voltage $V_{DS}=V_{GS}, I_D=250\muA$ 0.4Static Drain-Source on-Resistance note3 $V_{GS}=4.5V, I_D=30A$ -Nuput Capacitance $V_{DS}=10V, V_{GS}=0V,$ f = 1.0MHz-Output Capacitance $V_{DS}=10V, V_{GS}=0V,$ f = 1.0MHz-Total Gate Charge $V_{DS}=10V, I_D=30A,$ $V_{GS}=4.5V$ -Gate-Drain("Miller") ChargeTurn-on Delay Time $V_{DS}=10V,$ $V_{GS}=4.5V$ -Turn-on Rise Time $V_{DS}=10V,$ $I_D=30A,$ $V_{GS}=4.5V$ -Turn-off Delay Time $V_{GS}=4.5V$ -Turn-off Fall TimeMaximum Continuous Drain to Source Diode Forward Current-Maximum Pulsed Drain to Source Diode Forward Current-	$ \begin{array}{ c c c c } \hline Prime $	Drain-Source Breakdown Voltage $V_{GS}=0V, I_D=250\muA$ 20Drain-Source Breakdown Voltage $V_{GS}=0V, V_{GS}=0V,$ Zero Gate Voltage Drain Current $V_{DS}=20V, V_{GS}=0V,$ 1.0Gate to Body Leakage Current $V_{DS}=0V, V_{GS}=\pm12V$ ±100 Gate Threshold Voltage $V_{DS}=V_{GS}, I_D=250\muA$ 0.40.71.1Static Drain-Source on-Resistance $V_{GS}=4.5V, I_D=30A$ 4.05note3 $V_{GS}=2.5V, I_D=20A$ 6.09Input Capacitance $V_{DS}=10V, V_{GS}=0V,$ f = 1.0MHz407Output Capacitance $V_{DS}=10V, I_D=30A,$ $V_{GS}=4.5V$ 32Gate-Drain("Miller") Charge $V_{DS}=10V, I_D=30A,$ $V_{GS}=4.5V$ 11Turn-on Delay Time $V_{DS}=10V,$ $I_D=30A, R_{GEN}=3\Omega,$ $V_{GS}=4.5V$ 17Turn-off Delay Time $V_{DS}=10V,$ $I_D=30A, R_{GEN}=3\Omega,$ $V_{GS}=4.5V$ 17Turn-off Fall Time $V_{DS}=10V,$ $I_D=30A, R_{GEN}=3\Omega,$ $V_{GS}=4.5V$ 17Maximum Continuous Drain to Source Diode Forward Current75Maximum Pulsed Drain to Source Diode Forward Current

Electrical Characteristics (TJ=25°C unless otherwise specified)

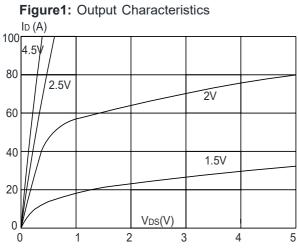
Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

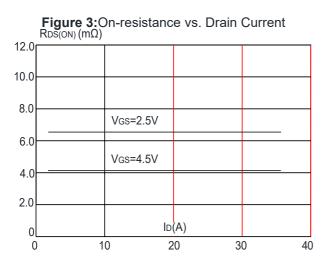
2. EAS condition: T_J=25 $^\circ\!\!\mathrm{C}$, V_DD=10V, V_G=4.5V, L=0.5mH, R_G=25 $^\Omega$, I_As=15A

3. Pulse Test: Pulse Width≤300µs, Duty Cycle≤0.5%

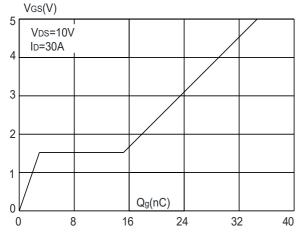


Typical Performance Characteristics



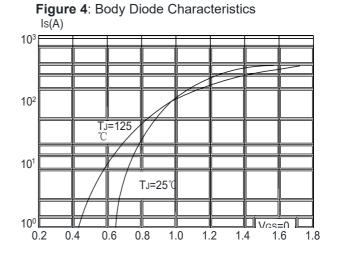




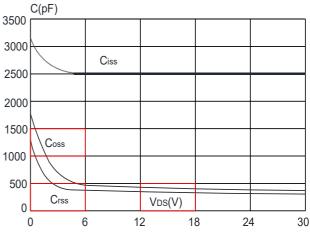


ID (A) 100 80 60 **125℃** 40 **25℃** 20 ′¢s(V) 0 0.5 1.0 1.5 2.0 2.5 3.0 0

Figure 2: Typical Transfer Characteristics









VBR(DSS) 1.3 1.2 1.1 1.0 0.9 Tj(℃) 0 -100 -50 0 50 100 200 150

Figure 9: Maximum Safe Operating Area

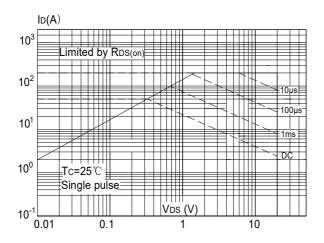
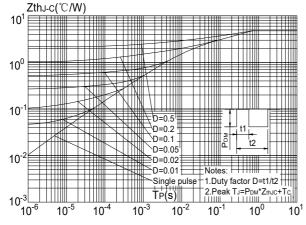


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Case



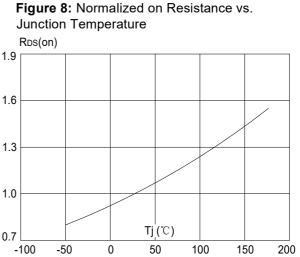
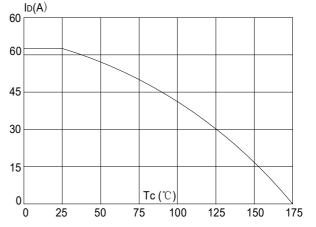
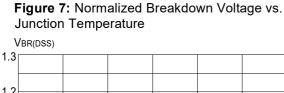


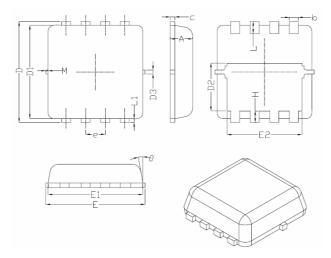
Figure 10: Maximum Continuous Drain Current vs. Case Temperature







DFN3X3-8L(TSON-8(3.1x3.1)) Package Information



Symbol	Dimensions In Millimeters			
	Min.	Nom.	Max.	
A	0.70	0.75	0.80	
b	0.25	0.30	0.35	
С	0.10	0.15	0.25	
D	3.25	3.35	3.45	
D1	3.00	3.10	3.20	
D2	1.48	1.58	1.68	
D3	-	0.13	-	
E	3.20	3.30	3.40	
E1	3.00	3.15	3.20	
E2	2.39	2.49	2.59	
е	0.65BSC			
Н	0.30	0.39	0.50	
L	0.30	0.40	0.50	
L1	-	0.13	-	
М	*	*	0.15	
θ		10ຶ	12 [°]	



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